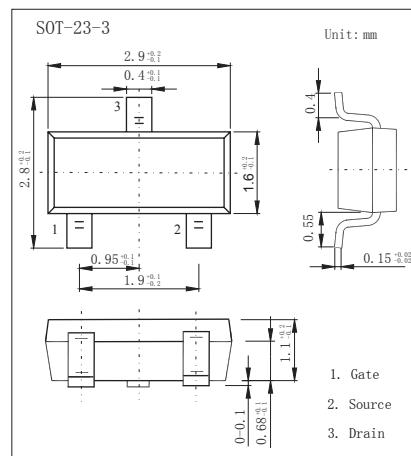
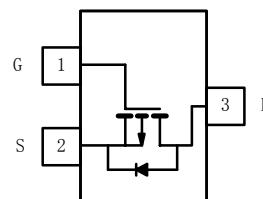


SOT-23-3 Plastic-Encapsulate MOSFETs**SI2301 P-Channel Enhancement MOSFET****■ Features**

- $V_{DS}(V) = -20V$
- $R_{DS(ON)} < 100m\Omega$ ($V_{GS} = -4.5V$)
- $R_{DS(ON)} < 150m\Omega$ ($V_{GS} = -2.5V$)

**■ Absolute Maximum Ratings $T_a = 25^\circ C$**

Parameter	Symbol	5 sec	Steady State	Unit
Drain-Source Voltage	V_{DS}	-20		V
Gate-Source Voltage	V_{GS}	± 8		
Continuous Drain Current $(T_a = 25^\circ C)^*1$	I_D	-2.4	-2.2	A
$T_a = 70^\circ C$		-1.9	-1.8	
Pulsed Drain Current *2	I_{DM}	-10		
Power Dissipation *1 $T_a = 25^\circ C$	P_D	0.9	0.7	W
$T_a = 70^\circ C$		0.57	0.45	
Thermal Resistance.Junction- to-Ambient *1 $*3$	R_{thJA}	120	145	$^\circ C/W$
		140	175	
Junction Temperature	T_J	150		
Storage Temperature Range	T_{stg}	-55 to 150		$^\circ C$

*1 Surface Mounted on FR4 Board, $t \leq 5$ sec.

*2 Pulse width limited by maximum junction temperature.

*3 Surface Mounted on FR4 Board.

■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V_{DSS}	$I_D=-250 \mu\text{A}, V_{GS}=0\text{V}$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-20\text{V}, V_{GS}=0\text{V}$			-1	μA
		$V_{DS}=-20\text{V}, V_{GS}=0\text{V}, T_J=55^\circ\text{C}$			-10	
Gate-Body leakage current	I_{GSS}	$V_{DS}=0\text{V}, V_{GS}=\pm 8\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250 \mu\text{A}$	-0.45		-0.95	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-4.5\text{V}, I_D=-2.8\text{A}$		80	100	$\text{m}\Omega$
		$V_{GS}=-2.5\text{V}, I_D=-2.0\text{A}$		110	150	
On state drain current *1	$I_{D(ON)}$	$V_{GS}=-4.5\text{V}, V_{DS} \leq -5\text{V}$	-6			A
		$V_{GS}=-2.5\text{V}, V_{DS} \leq -5\text{V}$	-3			
Forward Transconductance *1	g_{FS}	$V_{DS}=-5\text{V}, I_D=-2.8\text{A}$		6.5		S
Input Capacitance *2	C_{iss}	$V_{GS}=0\text{V}, V_{DS}=-6\text{V}, f=1\text{MHz}$		375		pF
Output Capacitance *2	C_{oss}			95		
Reverse Transfer Capacitance *2	C_{rss}			65		
Total Gate Charge *2	Q_g	$V_{GS}=-4.5\text{V}, V_{DS}=-6\text{V}, I_D=-2.8\text{A}$		4.5	10	nC
Gate Source Charge *2	Q_{gs}			0.7		
Gate Drain Charge *2	Q_{gd}			1.1		
Turn-On DelayTime *3	$t_{d(on)}$	$V_{GS}=-4.5\text{V}, V_{DS}=-6\text{V}, R_L=6 \Omega, R_{GEN}=6 \Omega$ $I_D=-1.0\text{A}$		20	30	ns
Turn-On Rise Time *3	t_r			40	60	
Turn-Off DelayTime *3	$t_{d(off)}$			30	45	
Turn-Off Fall Time *3	t_f			20	30	
Maximum Body-Diode Continuous Current	I_S	5 sec			-0.72	A
		Steady State			-0.6	
Diode Forward Voltage	V_{SD}	$I_S=-0.75\text{A}, V_{GS}=0\text{V}$		-0.8	-1.2	V

*1 Pulse test: $PW \leq 300\text{us}$ duty cycle $\leq 2\%$.

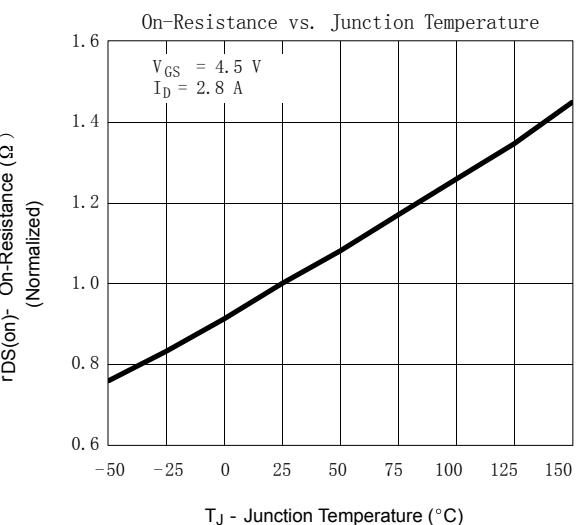
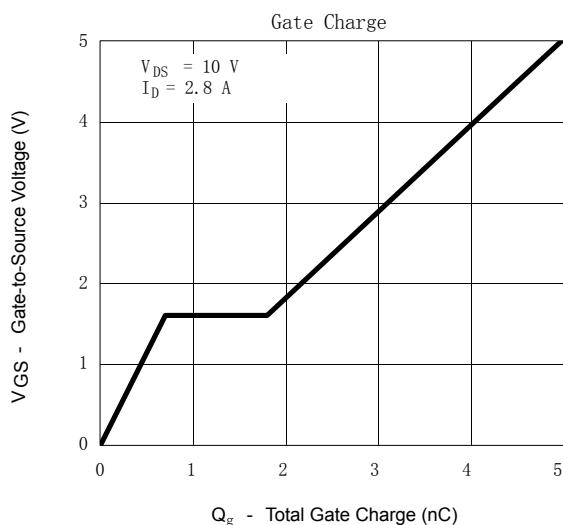
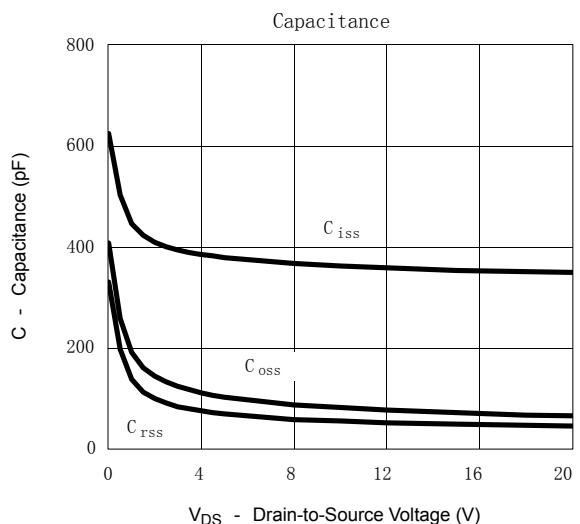
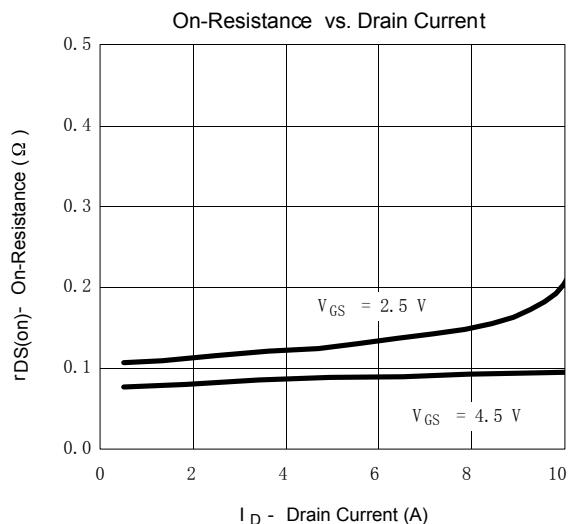
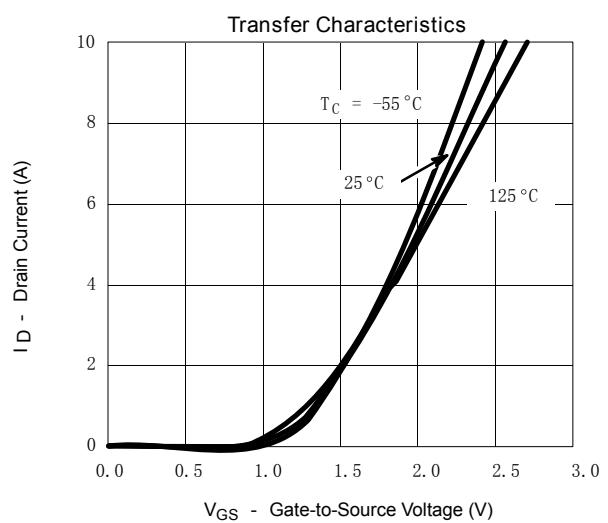
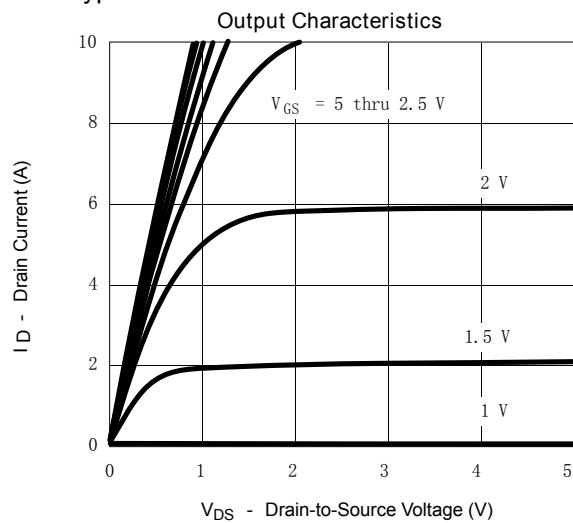
*2 For DESIGN AID ONLY, not subject to production testing.

*3 Switching time is essentially independent of operating temperature.

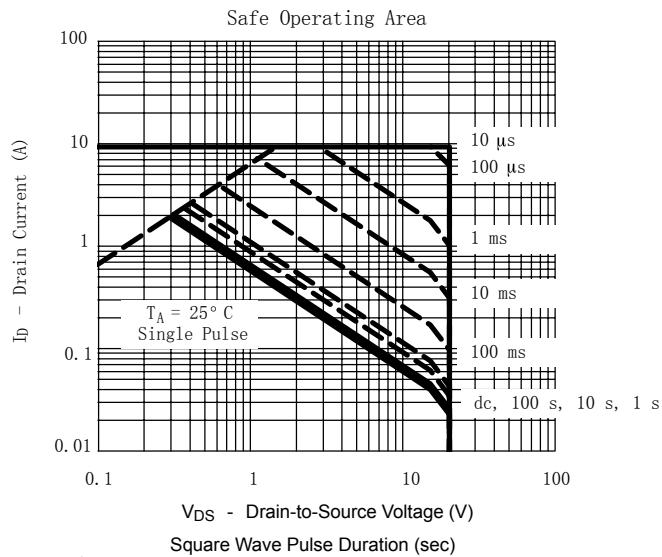
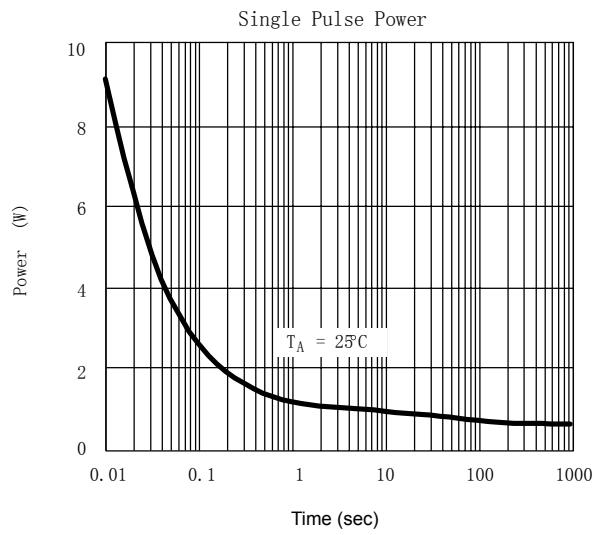
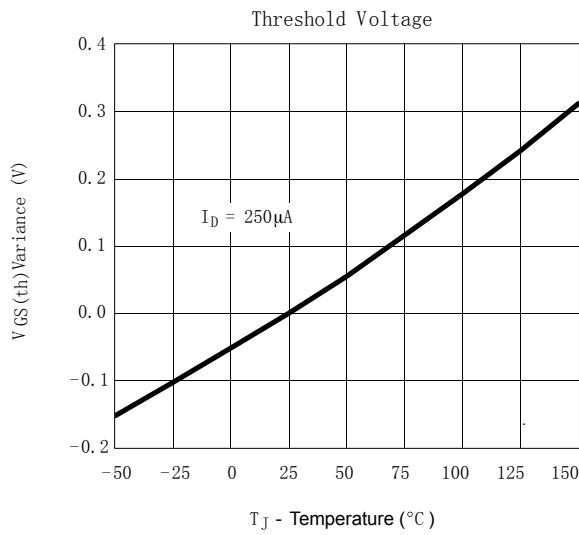
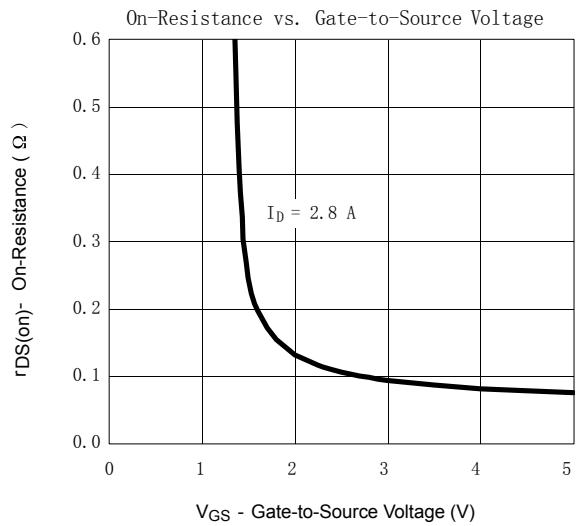
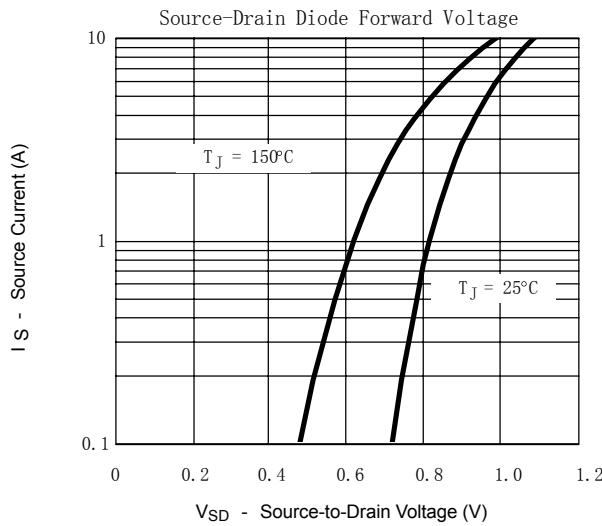
■ Marking

Marking	A1*
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■ Typical Characteristics



■ Typical Characteristics



■ Typical Characteristics